



07-31-2000



101418205

Docket No: SEL 170

In re application of: Hayakawa et al.

Serial No: 09/532,915

Filed: March 22, 2000

For: Semiconductor Device And Method For Manufacturing The Same)

Art Unit:

Examiner:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on July 20, 2000

## PATENT ASSIGNMENT COVER SHEET

Assistant Commissioner for Patents  
Washington, D. C. 20231

Cristine M. Duggan  
July 18, 2000

Sir:

Date

7/20/2000Please record the attached original document or copy thereof. Total number of pages (with cover sheet): 2

1. Name of Conveying Party(ies):  
Masahiko HAYAKAWA, Mitsunori SAKAMA and Satoshi TORIUMI

2a. Name and Address of Receiving Party(ies):  
Name: Semiconductor Energy Laboratory Co., Ltd.  
Address: 398, Hase, Atsugi-shi, Kanagawa-ken  
243-0036 Japan

2b. Name and Address of Receiving Party(ies):  
Name: \_\_\_\_\_  
Address: \_\_\_\_\_

3. Nature of Conveyance  
☒ Assignment  
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☐ Security Agreement  
☐ Change of Name  
☐ Other \_\_\_\_\_  
☒ Execution Date: 6/27/00

4. Application Number(s) or Patent number(s) (If this document is being filed together with a new application, the execution date of the application is: \_\_\_\_\_)

4a. Patent Application No.(s) 09/532,915

4b. Patent No.(s) \_\_\_\_\_

5. Name and Address of Party to Whom  
Correspondence Concerning Document Should be Mailed:

Edward D. Manzo, Esq.  
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200 West Adams Street, Suite 2850  
Chicago, Illinois 60606

6. Total Number of Applications and Patents  
Involved: 1

7. Total Fee (37 CFR 3.41): \$40.00  
7a. ☒ Enclosed  
7b. ☒ Authorized to be Charged to Deposit  
Account For Any Deficiency

8. Deposit Account Number: 50/1039  
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*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.*

Mark J. Murphy  
Name of Person Signing

Signature

Reg. No. 34,225

Date: July 18, 2000

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PATENT  
REEL: 010945 FRAME: 0776

**ASSIGNMENT**

**Identity Of The Patent Application.** I am the inventor (or one joint inventor) of a patent application that I am assigning. The patent application I am assigning is entitled SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING THE SAME which I executed herewith. If the patent application has already been filed, it received serial number 09/532,915 and bears a filing date of March 22, 2000.

**The Assignee and The Assignment.** I assign my patent rights to Semiconductor Energy Laboratory Co., Ltd. a corporation organized according to the laws of Japan, having a place of business at 398, Hase, Atsugi-shi, Kanagawa-ken 243-0036 Japan (hereinafter "the Assignee"). The rights I assign are my entire right, title and interest in the invention or improvements disclosed in the patent application and any and all other applications for United States Letters Patent which I may file, either solely or jointly with others, on the invention or improvements, including all continuations, divisionals, and continuations-in-part, and in any and all United States Letters Patent which may be obtained on any of said applications, and in any reissue or extension thereof. I also assign to the Assignee all priority rights under the International Convention. I agree to execute, at the request of the Assignee, all documents in connection with any application for United States letters patent therefor.

**Payment Received.** I am making this assignment in consideration of One Dollar and other good and valuable consideration. I acknowledge the receipt and sufficiency of the consideration.

**Authorizations.** I request the U.S. Commissioner of Patents and Trademarks to issue the Letters Patent to the Assignee. I authorize the attorney(s) of record in the application to insert in this assignment document the date and serial number of the application.

**Further Acts.** I agree, upon the request and at the expense of the Assignee, to execute any divisional, continuation or substitute application for the invention or improvements, and any oath, declaration or affidavit relating thereto, and any application for the reissue or extension of any Letters Patent that may be granted upon the application. I agree to perform, upon request, any affirmative acts to obtain said Letters Patent of the United States and to vest in the Assignee all rights therein, so that the Letters Patent will be held and enjoyed by the Assignee, to the full end of the term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me if this assignment had not been made.

**Interference.** In the event that any application or Letters Patent that I now assign becomes involved in interference, I agree to cooperate to the best of my ability in the matters of preparing and executing the preliminary statement and giving and producing evidence in support thereof.

Masahiko Hayakawa      06/27/2000  
Name: Masahiko HAYAKAWA      Date

Mitsunori Sakama      06/27/2000  
Name: Mitsunori SAKAMA      Date

Satoshi Toriumi      06/27/2000  
Name: Satoshi TORIUMI      Date

\_\_\_\_\_  
Name:      Date